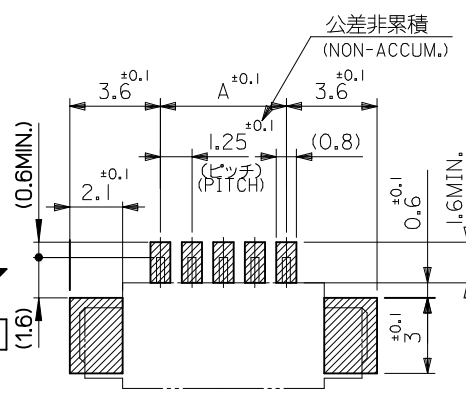
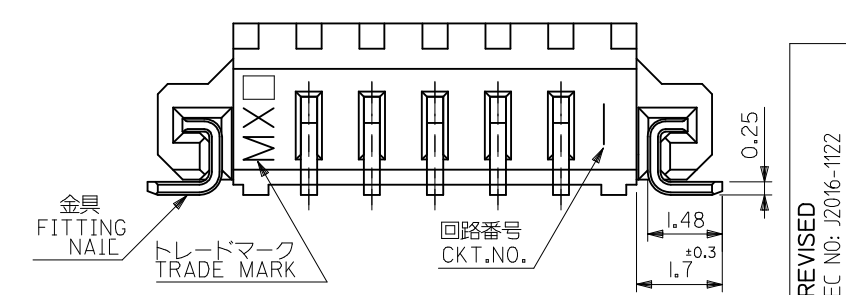
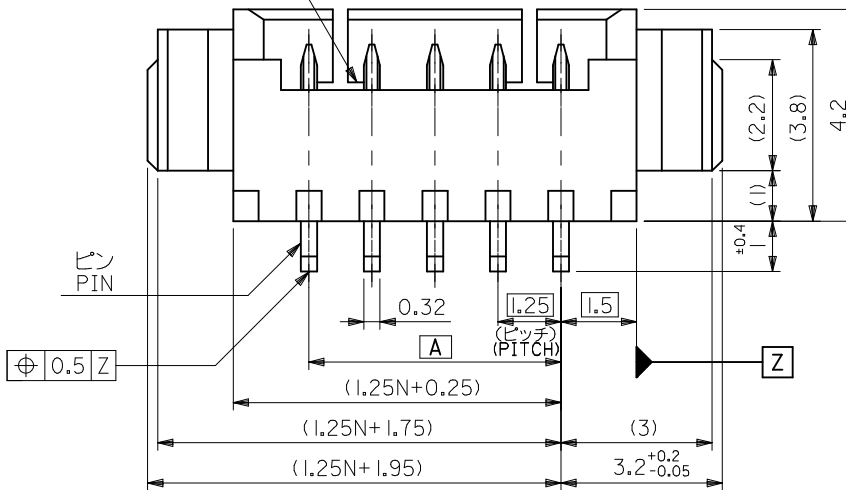
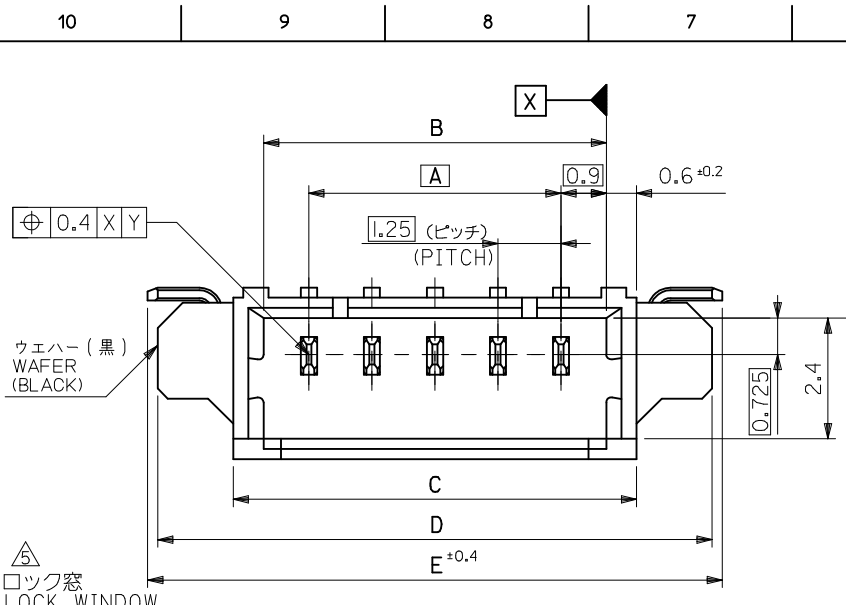
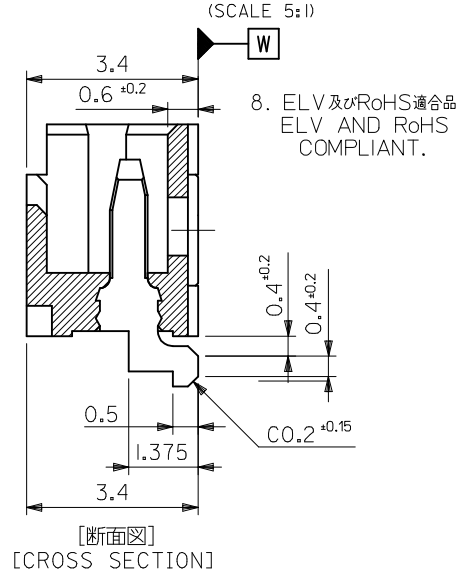


53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: YA0YAGI CHKD: YMAEDA APPR: NUKITA 2006/02/07 2006/02/03 2006/02/03	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	REV		MM ONLY	---	METRIC		
	0		10 UNDER ±---	DRAWN BY	DATE	TITLE	
			10 OVER 30 UNDER ±---	Y. A0YAGI	2006/01/30	1.25 W-T0-B CONN. 51021,53261 MATING CROSS SECTION	
			30 OVER ±---	CHECKED BY	DATE	MOLEX INCORPORATED	
		ANGULAR ±--- °	Y. MAEDA	2006/01/30	MATERIAL NO. DOCUMENT NO. SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY	DATE	SEE CHART SD-51021-002 1 OF 1		
			N. UKITA	2006/01/30	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)



注記 NOTES

- 嵌合相手: 51021 シリーズ
MATES WITH: 51021 SERIES
- 材質
MATERIAL
ウエハー: NYLON 46, UL94V-0 GLASS FILLED 30%
COLOR BLACK
ピン: リン青銅
PIN: PHOSPHOR BRONZE
金具: リン青銅
FITTING NAIL: PHOSPHOR BRONZE
- メッキ仕様
PLATING
ピン: 錫メッキ 1.0 μmMIN.
PIN: TIN 1.0 MICROMETER MIN.
下地メッキ: ニッケルメッキ 1.0 μmMIN.
UNDER-PLATING: NICKEL 1.0 MICROMETER MIN.
金具: 錫メッキ 1.0 μmMIN.
FITTING NAIL: TIN 1.0 MICROMETER MIN.
下地メッキ: ニッケルメッキ 1.0 μmMIN.
UNDER-PLATING: NICKEL 1.0 MICROMETER MIN.
- ソルダーテール部のスレ量及び金具(補強板)のスレ量は基準面 [W] に対し、上方向 0.05MAX.、下方向に 0.1 MAX. とする。
OFFSET BETWEEN BASIS PLANE [W] TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:
UPPER SIDE: 0.05MAX.
LOWER SIDE: 0.1MAX.
△ ロック窓は2、3極は1箇所、4極以上は2箇所とする。
LOCK WINDOW: ONE PLACE FOR 2 AND 3 CKTS. AND TWO PLACES FOR MORE THAN 3 CKTS.
- 本製品は 53261-**11, -**68 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**11, -**68.
- ソルダーテール及び金具の平坦度は 0.1 以下。
SOLDER TAIL & FITTING NAIL COPLANARITY TO BE 0.1 MAX.

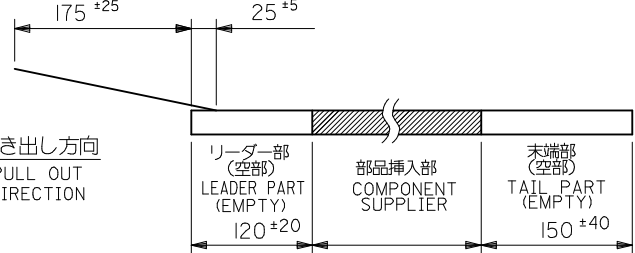
22.65	22.25	19.25	18.05	16.25	53261-1417	14
20.15	19.75	16.75	15.55	13.75	53261-1217	12
16.4	16	13	11.8	10	53261-0917	9
15.15	14.75	11.75	10.55	8.75	53261-0817	8
13.9	13.5	10.5	9.3	7.5	53261-0717	7
12.65	12.25	9.25	8.05	6.25	53261-0617	6
11.4	11	8	6.8	5	53261-0517	5
10.15	9.75	6.75	5.55	3.75	53261-0417	4
8.9	8.5	5.5	4.3	2.5	53261-0317	3
7.65	7.25	4.25	3.05	1.25	53261-0217	2

REVISED		EC NO: J2016-1122		2016/04/26		MODEL NO. 53261-**17	
G		DRWN: QHEJ1		2016/05/06		GENERAL TOLERANCES (UNLESS SPECIFIED)	
REV		CHKD: SAKIYAMA		2016/05/06		DIMENSION STYLE	
		APPR: IKANEKO		2016/05/06		MM ONLY	
DESCRIPTION		0.25 UNDER		UNDER		DRAWN BY	
		0.25 OVER		0.5 UNDER		DATE	
		0.5 OVER		1.0 UNDER		TITLE	
		1.0 OVER		10 UNDER		1.25 W/B CONN WAFER ASSY	
		10 OVER		30 UNDER		FOR SMT R/A	
		30 OVER				molex	
		ANGULAR		±3 °		SD-53261-025	
						SHEET NO.	
						1 OF 1	
						THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

注記
NOTES

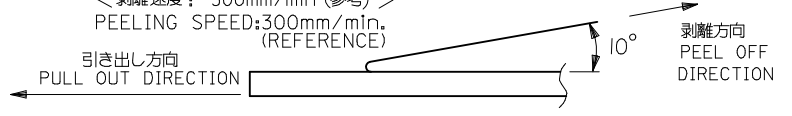
- 53261-**-17 の詳細寸法については図面 SD-53261-025 を参照下さい。
RE DETAILED DIMENSIONS,SEE SD-53261-025
- 梱包数量：1000個/リール
NUMBER OF CONNECTOR:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

トップテープリーダ部 トップテープ未接着部
TOP TAPE LEADER PART TOP TAPE NON-BONDED PART



- トップテープの剥離強度：0.1~1.3N {10 ~ 130gf} (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE: 0.1~1.3N {10 ~ 130gf}
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)

<剥離速度：300mm/min(参考)>
PEELING SPEED:300mm/min.
(REFERENCE)



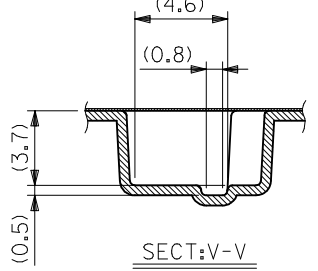
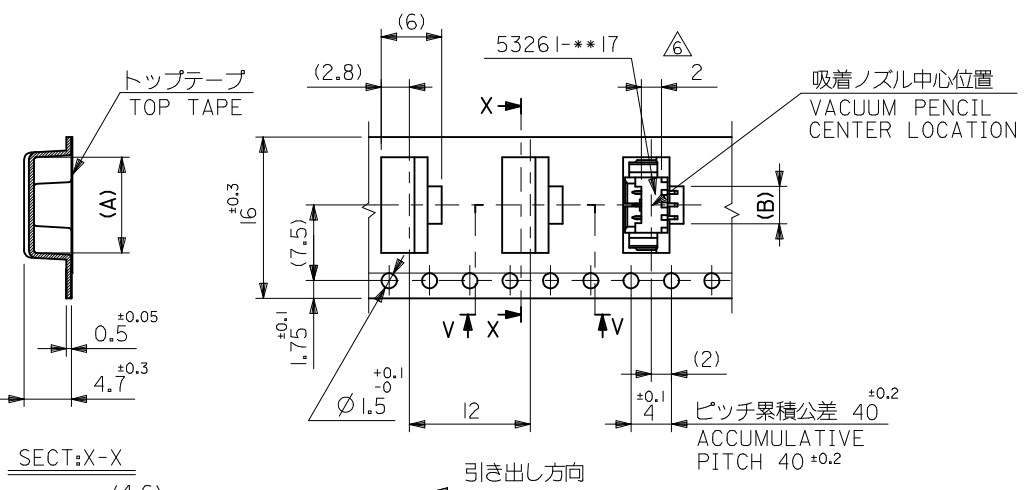
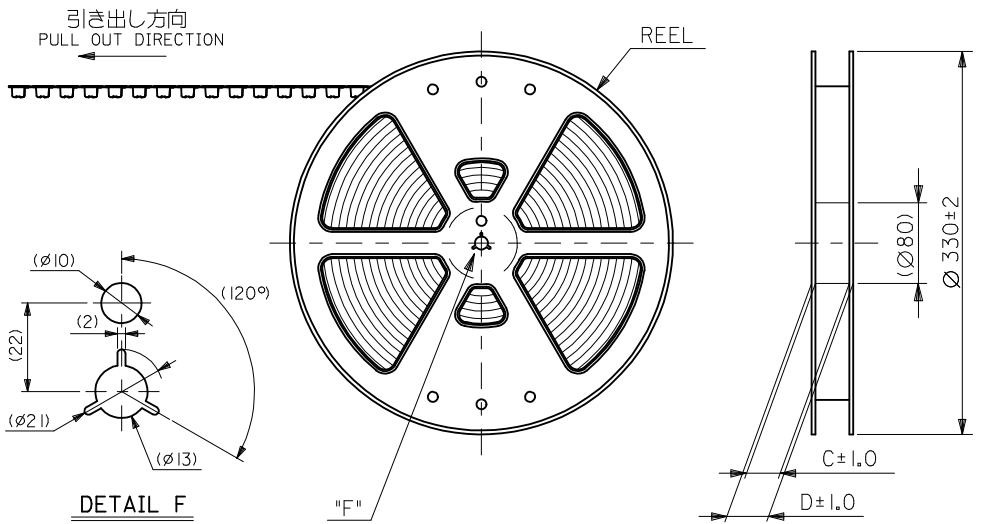
- 材料 (MATERIAL)
キャリアテープ(CARRIER TAPE):ポリプロピレン(POLYPROPYLENE)
トップテープ (TOP TAPE): PET ,PE ,PEF
リール (REEL):ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>

△ コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA

- 本製品は53261-**-95, -**-98の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-95, -**-98.

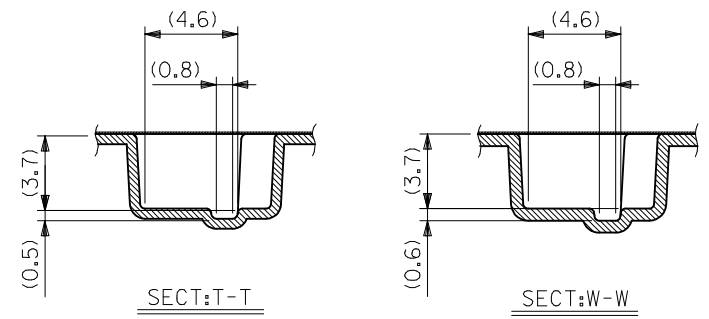
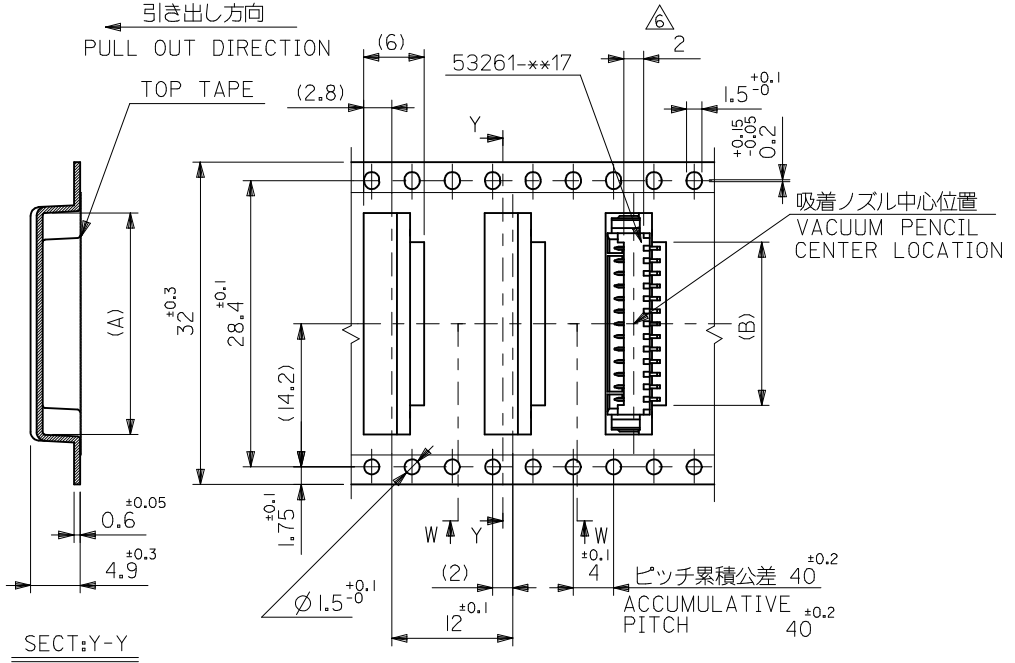
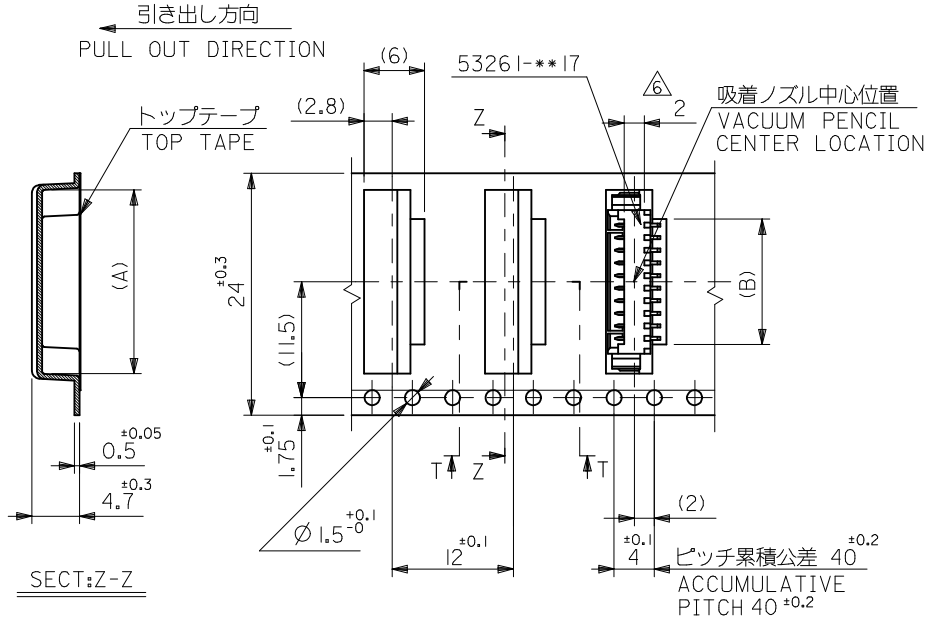
- 本製品は乾燥剤入り、ハイバリア梱包品である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

16	21.4	17.4	2.45	8.25	53261-0227	2
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL NO.	極数 CKT.
					MODEL NO.	53261-**-27



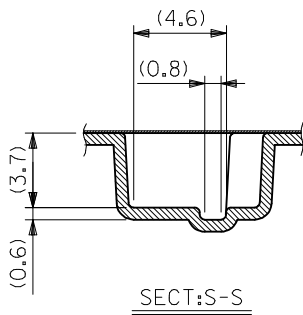
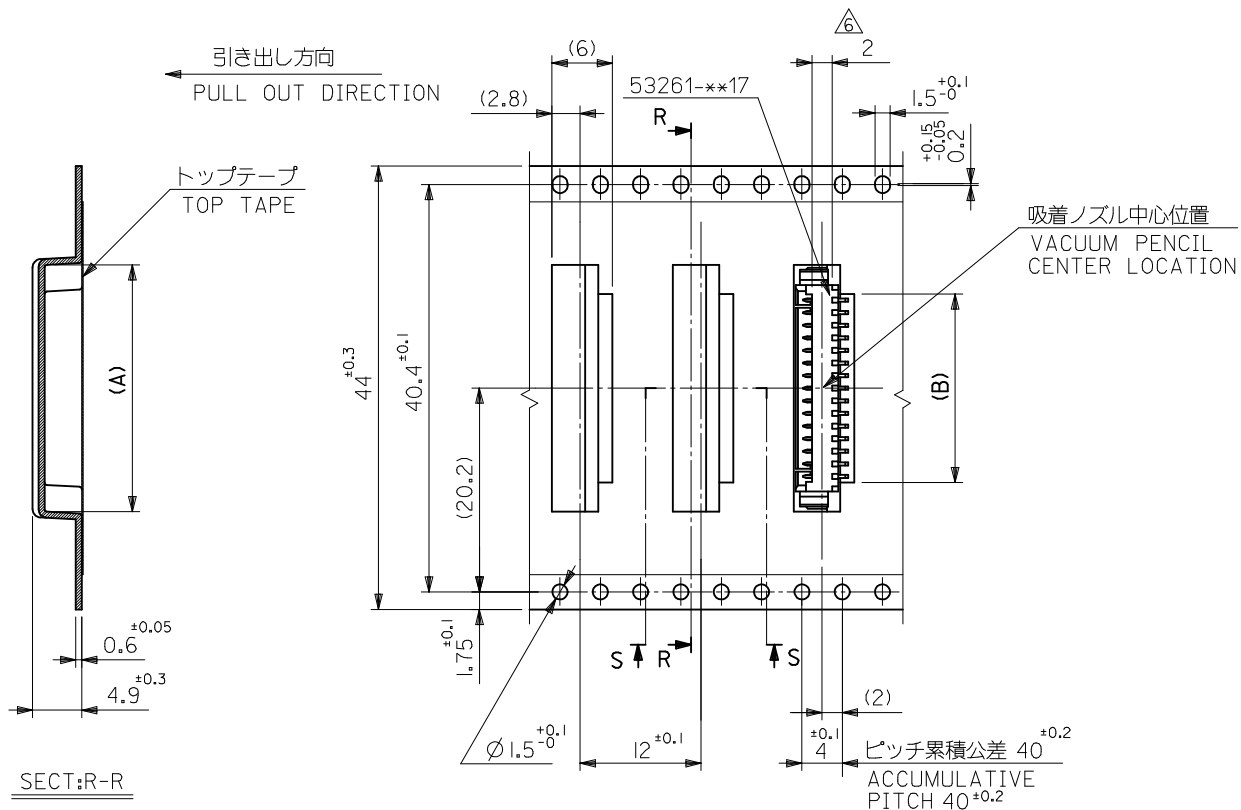
REVISED EC NO: J2009-2060 DRWN:TKON 2009/05/20 CHKD:HATSUMOTO 2009/05/21 APPR:NIKI ITA 2009/05/21	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	10 UNDER	±0.2
	10 OVER 30 UNDER	±0.25
	30 OVER	±0.3
DESCRIPTION	ANGULAR	±3 °
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY Y. WADA	DATE '04/04/12	TITLE 1.25 W/B CONN. WAFER ASSY SMT EMBSTP PKG -LEAD FREE-	
CHECKED BY M. SASAO	DATE '04/04/12	MOLEX INCORPORATED	
APPROVED BY M. SASAO	DATE '04/04/12	DOCUMENT NO. SD-53261-026	SHEET NO. 1 OF 3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



32	37.4	33.4	14.95	20.75	53261-1227	12
24	29.4	25.4	11.2	17	53261-0927	9
			9.95	15.75	53261-0827	8
			8.7	14.5	53261-0727	7
			7.45	13.25	53261-0627	6
			6.2	12	53261-0527	5
			4.95	10.75	53261-0427	4
			3.7	9.5	53261-0327	3
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL NO.	極数 CKT.

REVISED EC NO: J2009-2060 DRWN:TKON 2009/05/20 CHKD:HATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21 REV D	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE		
	10 OVER 30 UNDER	±0.25	Y. WADA	'04/04/12	1.25 W/B CONN. WAFER ASSY SMT EMBSTP PKG -LEAD FREE-		
	30 OVER	±0.3	M. SASAO	'04/04/12	MOLEX INCORPORATED		
ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY M. SASAO '04/04/12		MATERIAL NO. SEE CHART	DOCUMENT NO. SD-53261-026	SHEET NO. 2 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE

44	49.5	45.4	17.45	23.25	53261-1427	14
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL NO.	極数 CKT.
					MODEL NO.	53261-**27

REVISED EC NO: J2009-2060 DRWN:TKON CHKD:HATSUMOTO APPR:NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY Y. WADA	DATE '04/04/12	TITLE 1.25 W/B CONN. WAFER ASSY SMT EMBSTP PKG -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '04/04/12	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/04/12	DOCUMENT NO. SD-53261-026			
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		SHEET NO. 3 OF 3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

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